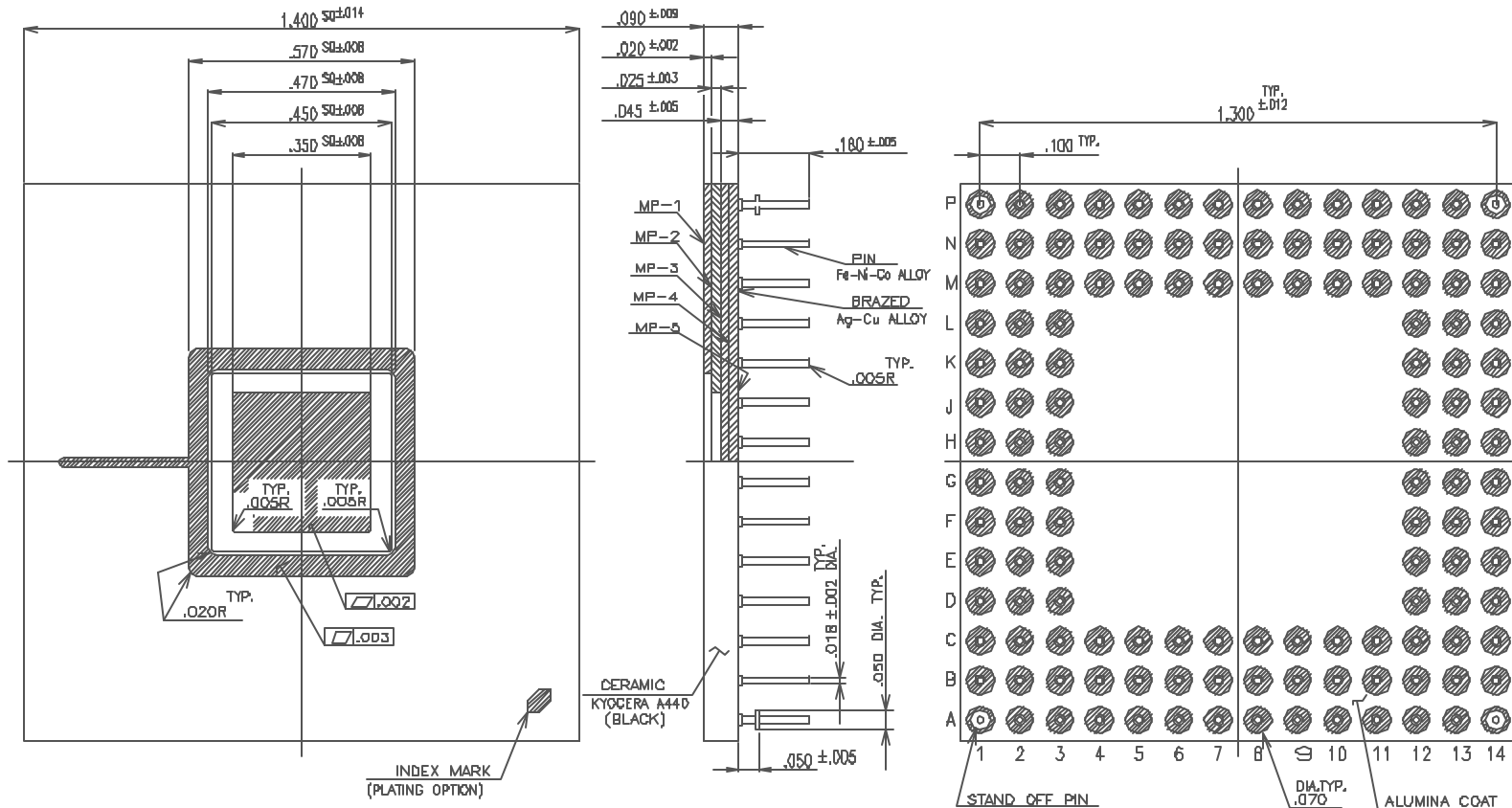


SSM P/N CPG13204



- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE :
 B/F NO.1,18,17,54,48,50,57,82,83,100,118,118 ---- 200m OHM MAX
 THE OTHERS ----- 1500 mOHM MAX.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						132 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.M.	S.A.	T.A.	MAY.9, '87
						SCALE 5/1	MATERIAL AS INDICATED				
							±.005				
	CHANGED		DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION		DRAWING NO.	SHEET
							KYOTO JAPAN	KD-P87350		1/3	



